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	FORM COVER SHEET
	ENTS ONLY
DOCKET NUMBER: 2020 To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.	
	Name and address of receiving party(les)
Name of conveying party(ies): General Semiconductor Ireland	,
	Name: <u>General Semiconductor, Inc.</u>
	Internal Address:
Additional name(s) of conveying party(ies) attached? Yes X No	
Name of conveyance: X Assignment Merger	Street Address: <u>10 Melville Park Road</u>
Security Agreement Change of Name	City: <u>Melville</u> State: <u>NY</u> Zip: <u>11747-3113</u>
Other	·
Execution Date: <u>09/30/2003</u>	Additional name(s) & address(es) Yes X No attached?
4. Application number(s) or patent number(s): If this document is being filed together with a new applicati A. Patent Application No.(s) 10/617,343 Additional numbers attached	B. Patent No.(s) 5,083,193 5,814,874 6,197,618
Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:
Name: <u>Karin L. Williams</u>	7. Total fee (37 CFR 3.41) \$160.00
Internal Address: Mayer Fortkort & Williams, PC	Enclosed
	X Authorized to be charged to deposit account
Street Address: 251 North Avenue West, 2 nd Floor	8. Deposit account number: 50-1047
City: Westfield	
State: New Jersey Zip: 07090	(Attach duplicate copy of this page if paying by deposit account.)
DO NOT USE THIS SPACE	
9 Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a	
true copy of th	e original document
- Mayro	Date 3/19/09
Name of Person Signing Signatu Total number of pages including cover sheet, attachments,	
documents:	

Mail documents to be recorded with required cover sheet information to: Commissioner for Patents, Mail Stop Assignment, P.O. Box 1450, Alexandria, VA 22313-1450

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PATENT

ASSIGNMENT OF PATENTS

THIS ASSIGNMENT is made the 30th day of September 2003 BY AND BETWEEN GENERAL SEMICONDUCTOR IRELAND an Unlimited Liability Company organized and existing under the laws of the Republic of Ireland and having its registered office at C/O G.J. Moloney, Solicitors, Courthouse Chambers, 27/29 Washington Street, Cork, Republic of Ireland (hereinafter the "Assignor") of the one part and GENERAL SEMICONDUCTOR, INC a Company organized and existing under the laws of Delaware and having its place of business at 10 Melville Park Road, Melville, NY 11747 (hereinafter the "Assignee") of the other part.

WHEREAS:

- A. The Assignor is the legal and beneficial owner and registered proprietor of certain letters, patents and patent applications as set forth in Schedule One attached hereto and made a part hereof (hereinafter the "Patents").
- B. The Assignee is an affiliated Company of the Assignor.
- C. The Assignor has ceased to manufacture from its facility in Macroom, County Cork, Republic of Ireland and is in the process of winding down its operations generally and it has therefore been agreed between the parties that the Assignor will assign its interest in the Patents to the Assignee in accordance with the terms and conditions hereof.

NOW THIS DEED WITNESSES AS FOLLOWS:

- 1. The Assignor hereby assigns, transfers and sets over to the Assignee the Patents together with all the rights, title and interest of the Assignor in or in respect of the Patents, the inventions to which they relate and in any improvements thereto TO HOLD, USE, EXERCISE AND ENJOY THE PATENTS unto and by the Assignee, its Successors and Assigns absolutely.
- 2. In consideration of the assignment of the Patents the Assignee agrees to pay to the Assignor the amount of US\$1,000 (the receipt of which is hereby acknowledged).

PATENT REEL: 014446 FRAME: 0129 Duly executed for and on behalf

- 3. This Assignment and the respective rights and obligations of the parties hereunder shall be governed by and construed in accordance with the laws of Ireland.
- 4. This Assignment may be executed in any number of counterparts with the same effect as if executed upon the same instrument.

IN WITNESS WHEREOF this Assignment has been duly executed the day and year first above written.

	1 1
By	2010
Rainer Kropf	
In the presence of	1-800
	Gudrun Böhr
477	(Please type or print name)
Duly executed for and on behalf	
of General Semico	Aductor, Inc.
	11 7/1/1
By	lugsuVII.
	N. Grube
	N. Grubel
	N. Grub

(Please type or print name)

PATENT

REEL: 014446 FRAME: 0130

SCHEDULE ONE

1. U.S. Patent No. 5,083,193

Issued: January 21, 1992

Title: SEMICONDUCTOR PACKAGE, METHOD OF MANUFACTURING THE SAME, APPARATUS FOR CARRYING OUT THE METHOD, AND

ASSEMBLY FACILITY Inventor: Viktor Heitzler et al.

2. U.S. Patent No. 5,814,874

Issued: September 29, 1998

Title: SEMICONDUCTOR DEVICE HAVING A SHORTER SWITCHING

TIME WITH LOW FORWARD VOLTAGE

Inventor: Guenter Igel

3. U.S. Patent No. 6,197,618

Issued: March 6, 2001

Title: SEMICONDUCTOR DEVICE FABRICATION USING ADHESIVES

Inventor: Marie Guillot et al.

4. U.S. Patent Application SN. 10/617,343

Filed: July 10, 2003

Title: SURFACE MOUNT MULTICHIP DISCRETE STRUCTURE

Inventor: Paddy O'Shea et al.

RECORDED: 03/19/2004

PATENT

REEL: 014446 FRAME: 0131